

SciTech 2021 Call for Papers

Supplemental Information for Survivability

Joint Session, Sponsored by the Survivability and Materials Technical Committees: Materials for Survivability

Survivability improvements for air and space systems increasingly rely on the development of new materials and composites, which must be lightweight but also satisfy a demanding set of mechanical, thermal, electromagnetic, or other requirements. Examples include: (1) high toughness composite materials for aircraft, (2) impact resistant thermal protection materials for spacecraft, (3) low observability coatings which reduce optical or radar signatures, (4) smart materials which support structural health monitoring or self-healing, and (5) additively manufactured materials with properties optimized for specific applications. Abstracts describing analytical, computational, experimental, or design research which address any aspect of the 'materials for survivability' theme are encouraged.

Interested authors may contact Eric Fahrenthold (epfahren@mail.utexas.edu) or Joe Koo (jkoo@mail.utexas.edu).

Joint Session, Sponsored by the Survivability and Structures Technical Committees: Structures for Survivability

Survivability improvements for air and space systems increasingly rely on the development of new structural designs, which must be lightweight but also satisfy a demanding set of mechanical, thermal, electromagnetic, or other requirements. Examples include: (1) improved ballistic protection systems for rotary wing aircraft, (2) improved thermal protection systems for spacecraft, (3) low observability structures, (4) designs which incorporate structural health monitoring or self-healing, (5) additively manufactured structural components with properties optimized for specific applications, and (6) novel structural designs for impact mitigation and stress wave management. Abstracts describing analytical, computational, experimental, or design research which address any aspect of the 'survivable structures' theme are encouraged.

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